FAIRCHILD

May 2014

FDMS7602S

Dual N-Channel PowerTrench® MOSFET

Q1: 30 V, 30 A, 7.5 mΩ Q2: 30 V, 30 A, 5.0 mΩ

Features

Q1: N-Channel

- Max $r_{DS(on)}$ = 7.5 mΩ at V_{GS} = 10 V, I_D = 12 A
- Max $r_{DS(on)}$ = 12 mΩ at V_{GS} = 4.5 V, I_D = 10 A

Q2: N-Channel

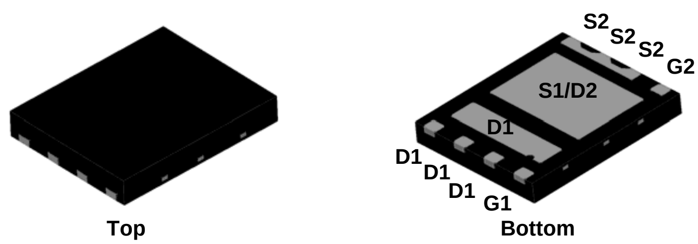
- Max $r_{DS(on)}$ = 5.0 mΩ at V_{GS} = 10 V, I_D = 17 A
- Max $r_{DS(on)}$ = 6.8 mΩ at V_{GS} = 4.5 V, I_D = 14 A
- RoHS Compliant

General Description

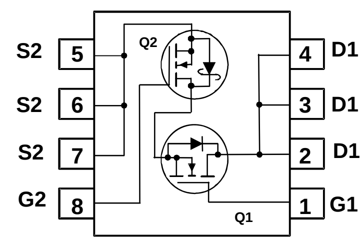
This device includes two specialized N-Channel MOSFETs in a dual MLP package.The switch node has been internally connected to enable easy placement and routing of synchronous buck converters. The control MOSFET (Q1) and synchronous SyncFET^{TM} (Q2) have been designed to provide optimal power efficiency.

Applications

- Computing
- Communications
- General Purpose Point of Load
- Notebook VCORE



Power 56



MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Parameter		Q1	Q2	Units
V_{DS}	Drain to Source Voltage		30	30	V
V_{GS}	Gate to Source Voltage	(Note 3)	±20	±20	V
I_D	Drain Current -Continuous	T_C = 25 °C	30	30	A
	-Continuous	T_A = 25 °C	12[1a]	17[1b]	
	-Pulsed		40	60	
P_D	Power Dissipation for Single Operation	T_A = 25 °C	2.2[1a]	2.5[1b]	W
	Power Dissipation for Single Operation	T_A = 25 °C	1.0[1c]	1.0[1d]	
T_J, T_{STG}	Operating and Storage Junction Temperature Range		-55 to +150		°C

Thermal Characteristics

Symbol	Parameter	Q1	Q2	Units
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	57[1a]	50[1b]	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	125[1c]	120[1d]	
$R_{\theta JC}$	Thermal Resistance, Junction to Case	3.5	2	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS7602S	FDMS7602S	Power 56	13 ”	12 mm	3000 units

Electrical Characteristics T_J = 25 °C unless otherwise noted

Symbol	Parameter	Test Conditions	Type	Min	Typ	Max	Units

Off Characteristics

Symbol	Parameter	Test Conditions	Type	Min	Typ	Max	Units
BV_{DSS}	Drain to Source Breakdown Voltage	I_D = 250 μA, V_{GS} = 0 V I_D = 1 mA, V_{GS} = 0 V	Q1 Q2	30 30			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μA, referenced to 25 °C I_D = 1 mA, referenced to 25 °C	Q1 Q2		15 15		mV/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 24 V, V_{GS} = 0 V	Q1 Q2			1 500	μA μA
I_{GSS}	Gate to Source Leakage Current	V_{GS} = 20 V, V_{DS}= 0 V V_{GS} = 20 V, V_{DS}= 0 V	Q1 Q2			100 100	nA nA

On Characteristics

Symbol	Parameter	Test Conditions	Type	Min	Typ	Max	Units
$V_{GS(th)}$	Gate to Source Threshold Voltage	V_{GS} = V_{DS}, I_D = 250 μA V_{GS} = V_{DS}, I_D = 1 mA	Q1 Q2	1 1	1.8 1.8	3 3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μA, referenced to 25 °C I_D = 1 mA, referenced to 25 °C	Q1 Q2		-6 -5		mV/°C
$r_{DS(on)}$	Drain to Source On Resistance	V_{GS} = 10 V, I_D = 12 A V_{GS} = 4.5 V, I_D = 10 A V_{GS} = 10 V, I_D = 12 A , T_J = 125 °C	Q1		6.0 8.5 8.3	7.5 12 12	mΩ
		V_{GS} = 10 V, I_D = 17 A V_{GS} = 4.5 V, I_D = 14 A V_{GS} = 10 V, I_D = 17 A , T_J = 125 °C	Q2		4.2 5.4 4.9	5.0 6.8 7.2	
g_{FS}	Forward Transconductance	V_{DS} = 5 V, I_D = 12 A V_{DS} = 5 V, I_D = 17 A	Q1 Q2		63 87		S

Dynamic Characteristics

Symbol	Parameter	Test Conditions	Type	Min	Typ	Max	Units
C_{iss}	Input Capacitance	Q1: V_{DS} = 15 V, V_{GS} = 0 V, f = 1 MHZ Q2: V_{DS} = 15 V, V_{GS} = 0 V, f = 1 MHZ	Q1 Q2		1315 2020	1750 2690	pF
C_{oss}	Output Capacitance		Q1 Q2		445 860	600 1145	pF
C_{rss}	Reverse Transfer Capacitance		Q1 Q2		45 95	70 145	pF
R_g	Gate Resistance		Q1 Q2		0.9 0.7		Ω

Switching Characteristics

Symbol	Parameter	Test Conditions		Type	Min	Typ	Max	Units
$t_{d(on)}$	Turn-On Delay Time	Q1: V_{DD} = 15 V, I_D = 12 A, R_{GEN} = 6 Ω Q2: V_{DD} = 15 V, I_D = 17 A, R_{GEN} = 6 Ω		Q1 Q2		8.6 11	18 20	ns
t_r	Rise Time			Q1 Q2		2.5 3.8	10 10	ns
$t_{d(off)}$	Turn-Off Delay Time			Q1 Q2		20 27	32 43	ns
t_f	Fall Time			Q1 Q2		2.3 3.2	10 10	ns
Q_g	Total Gate Charge	V_{GS} = 0 V to 10 V	Q1 V_{DD} = 15 V, I_D = 12 A Q2 V_{DD} = 15 V, I_D = 17 A	Q1 Q2		20 33	28 46	nC
Q_g	Total Gate Charge	V_{GS} = 0 V to 4.5 V		Q1 Q2		9.3 16	13 22	nC
Q_{gs}	Gate to Source Gate Charge			Q1 Q2		4.3 5.8		nC
Q_{gd}	Gate to Drain “Miller” Charge			Q1 Q2		2.2 4.6		nC

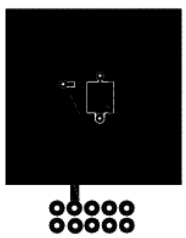
Electrical Characteristics T_J = 25 °C unless otherwise noted

Drain-Source Diode Characteristics

Symbol	Parameter	Test Conditions	Type	Min	Typ	Max	Units
V_{SD}	Source to Drain Diode Forward Voltage	V_{GS} = 0 V, I_S = 12 A (Note 2) V_{GS} = 0 V, I_S = 17 A (Note 2)	Q1 Q2		0.8 0.8	1.2 1.2	V
t_{rr}	Reverse Recovery Time	Q1 I_F = 12 A, di/dt = 100 A/µs	Q1 Q2		27 29	43 46	ns
Q_{rr}	Reverse Recovery Charge	Q2 I_F = 17 A, di/dt = 300 A/µs	Q1 Q2		10 31	18 50	nC

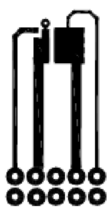
Notes:

1: $R_{\theta JA}$ is determined with the device mounted on a 1 in^2 pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.

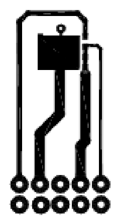


a. 57 °C/W when mounted on a 1 in^2 pad of 2 oz copper

b. 50 °C/W when mounted on a 1 in^2 pad of 2 oz copper



c. 125 °C/W when mounted on a minimum pad of 2 oz copper



d. 120 °C/W when mounted on a minimum pad of 2 oz copper

2: Pulse Test: Pulse Width < 300 µs, Duty cycle < 2.0%.

3: As an N-ch device, the negative Vgs rating is for low duty cycle pulse ocurrence only. No continuous rating is implied.

Typical Characteristics (Q1 N-Channel) T_J = 25°C unless otherwise noted

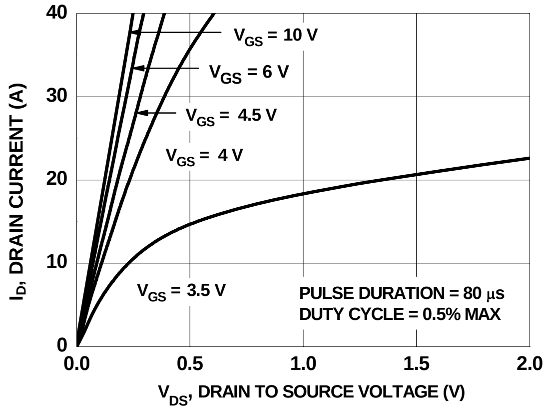


Figure 1. On Region Characteristics

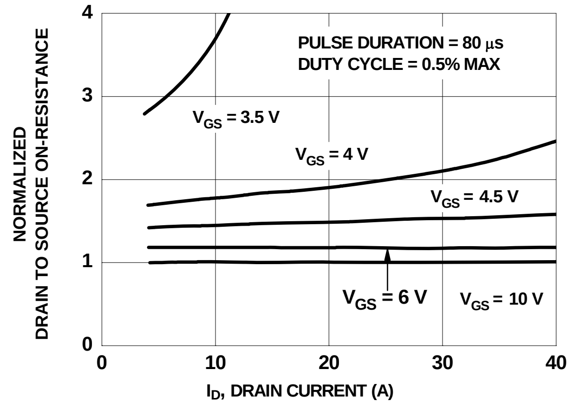


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

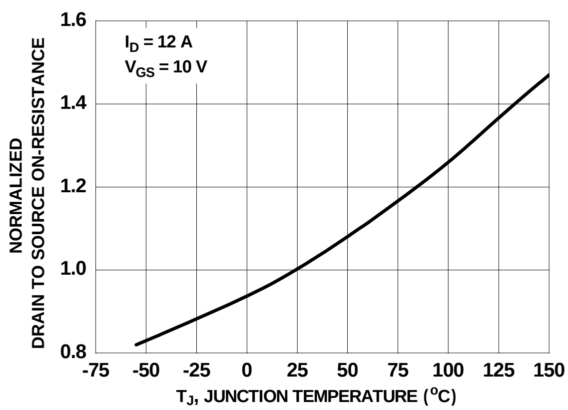


Figure 3. Normalized On Resistance vs Junction Temperature

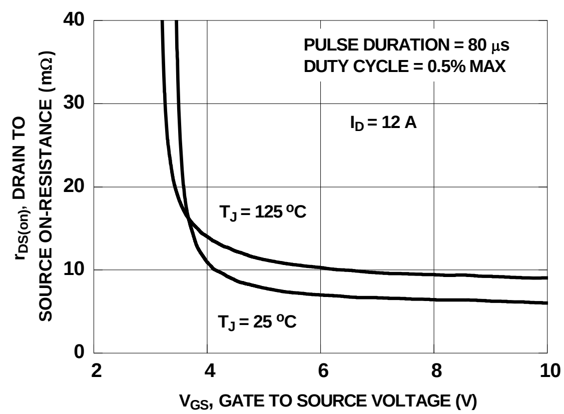


Figure 4. On-Resistance vs Gate to Source Voltage

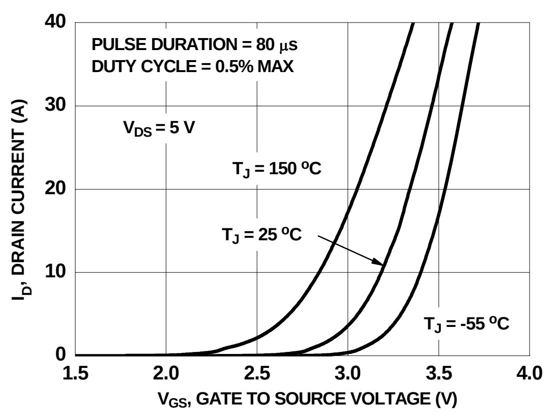


Figure 5. Transfer Characteristics

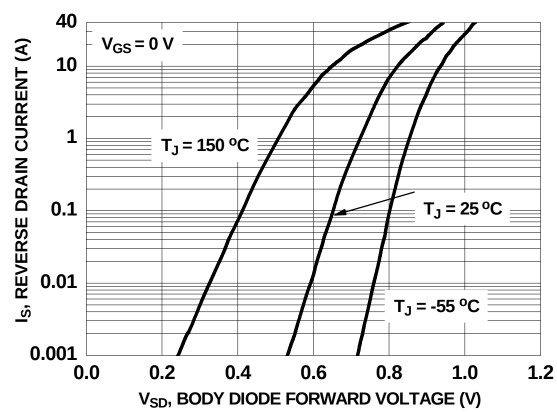


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics (Q1 N-Channel) T_J = 25°C unless otherwise noted

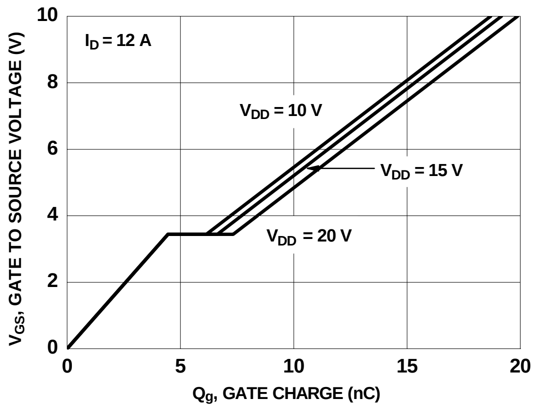


Figure 7. Gate Charge Characteristics

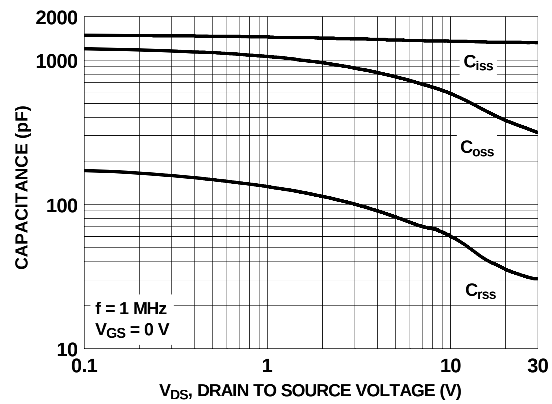


Figure 8. Capacitance vs Drain to Source Voltage

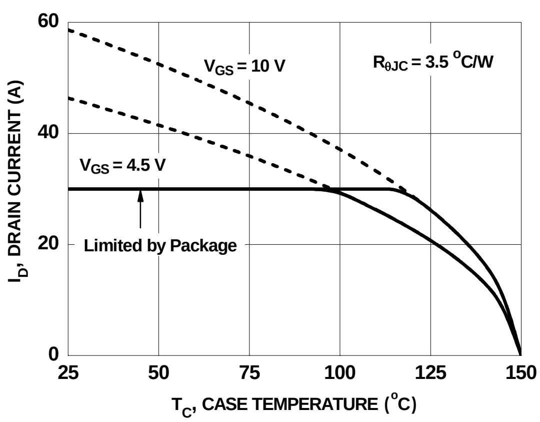


Figure 9. Maximum Continuous Drain Current vs Case Temperature

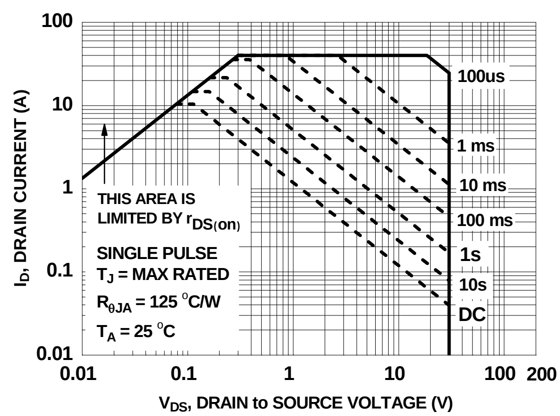


Figure 10. Forward Bias Safe Operating Area

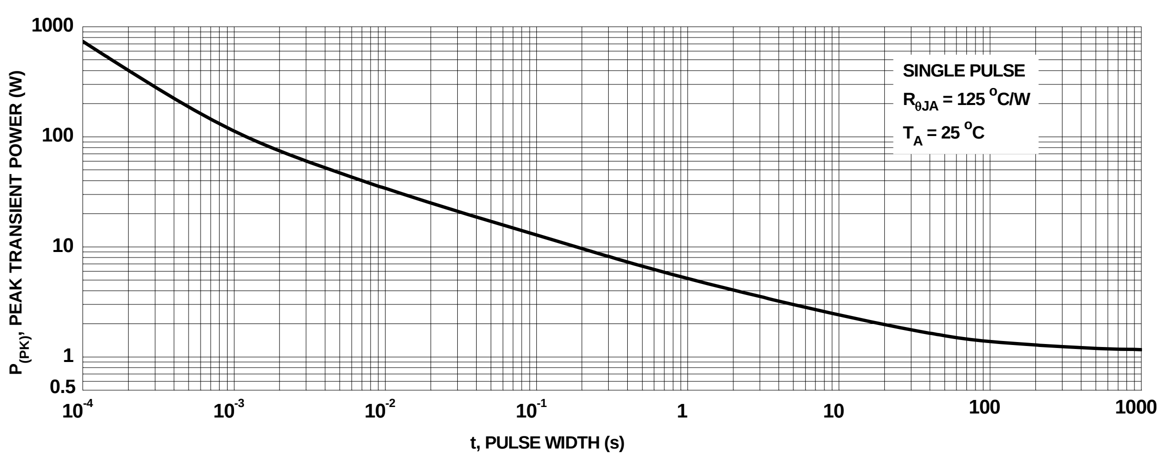


Figure 11. Single Pulse Maximum Power Dissipation

Typical Characteristics (Q1 N-Channel) T_J = 25°C unless otherwise noted

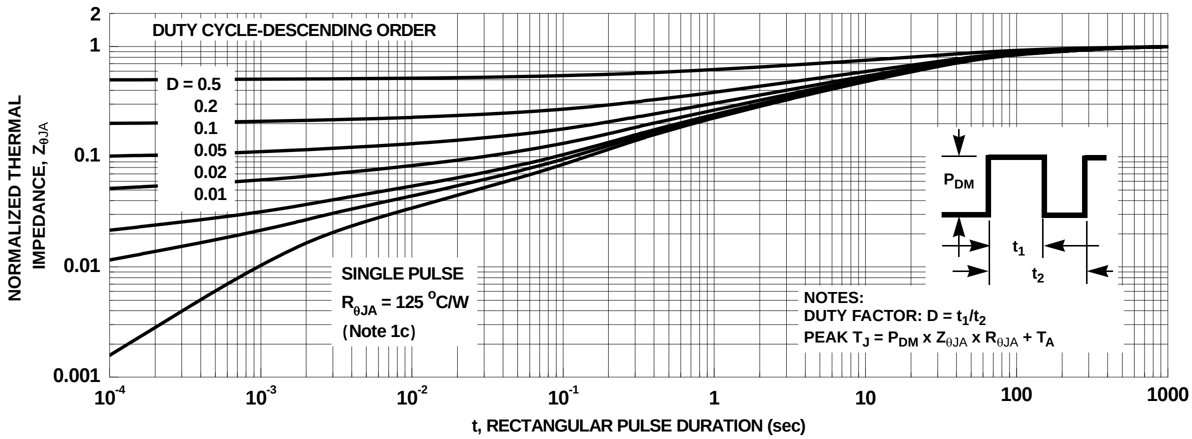


Figure 12. Junction-to-Ambient Transient Thermal Response Curve

Typical Characteristics (Q2 SyncFET)

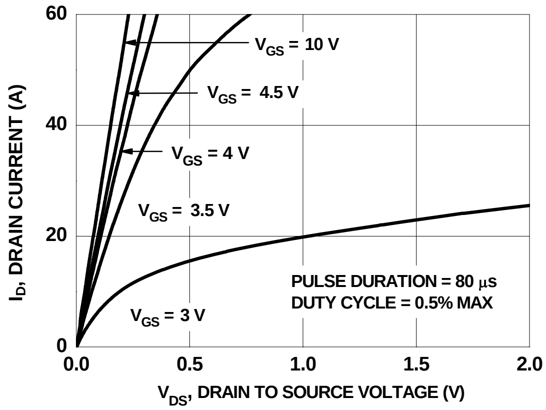


Figure 13. On-Region Characteristics

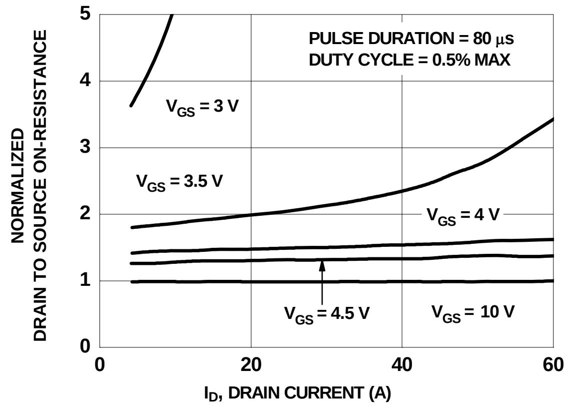


Figure 14. Normalized on-Resistance vs Drain Current and Gate Voltage

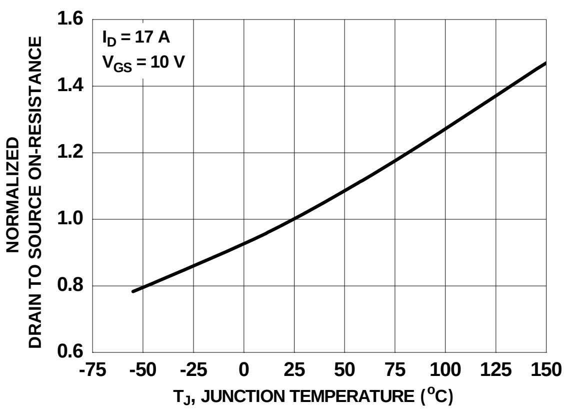


Figure 15. Normalized On-Resistance vs Junction Temperature

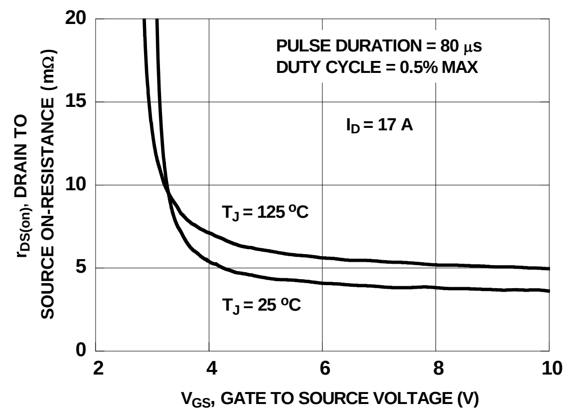


Figure 16. On-Resistance vs Gate to Source Voltage

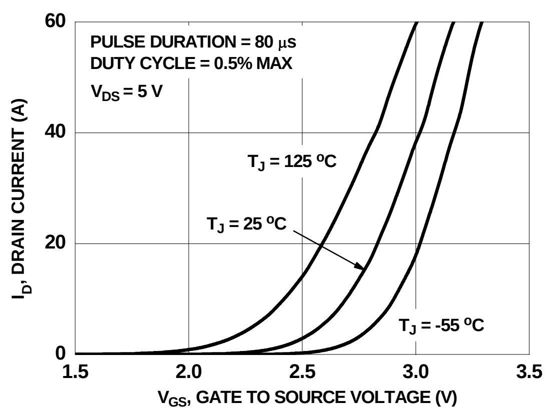


Figure 17. Transfer Characteristics

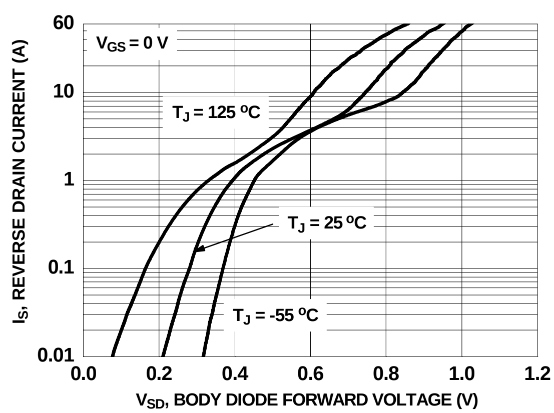


Figure 18. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics (Q2 SyncFET)

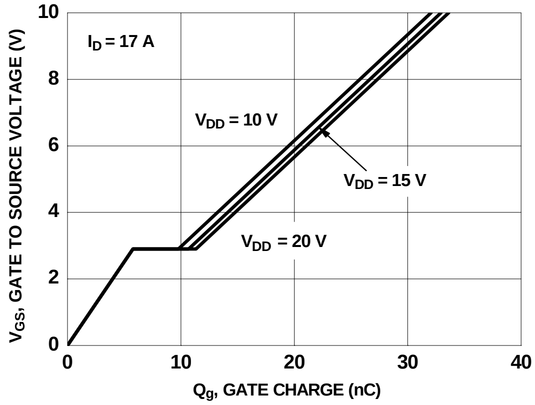


Figure 19. Gate Charge Characteristics

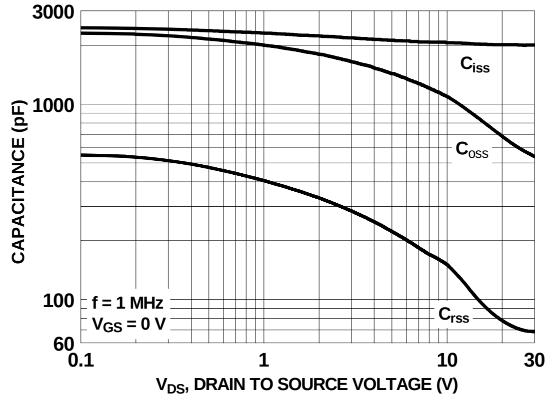


Figure 20. Capacitance vs Drain to Source Voltage

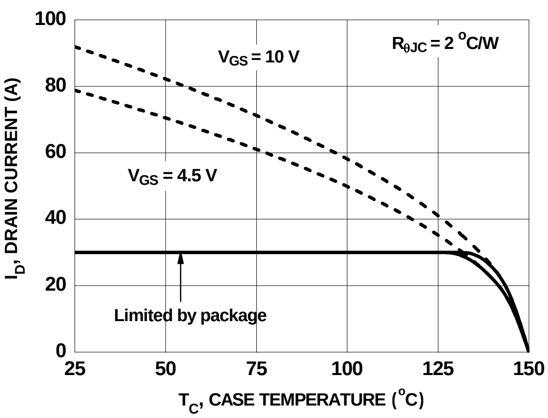


Figure 21. Maximum Continuous Drain Current vs Case Temperature

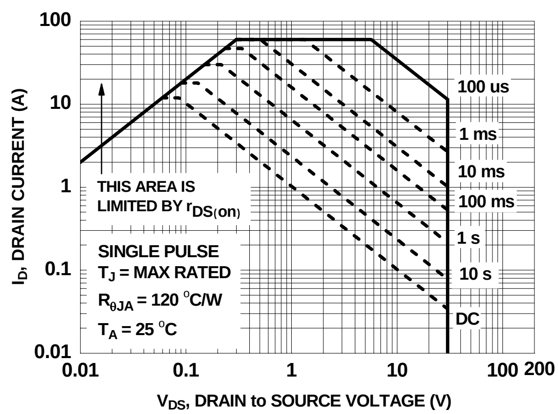


Figure 22. Forward Bias Safe Operating Area

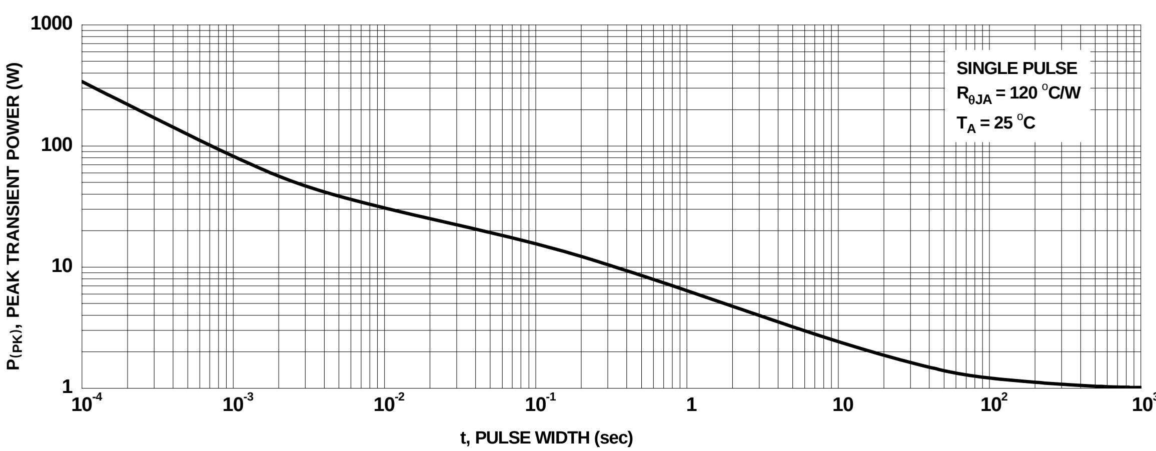


Figure 23. Single Pulse Maximum Power Dissipation

Typical Characteristics (Q2 SyncFET)

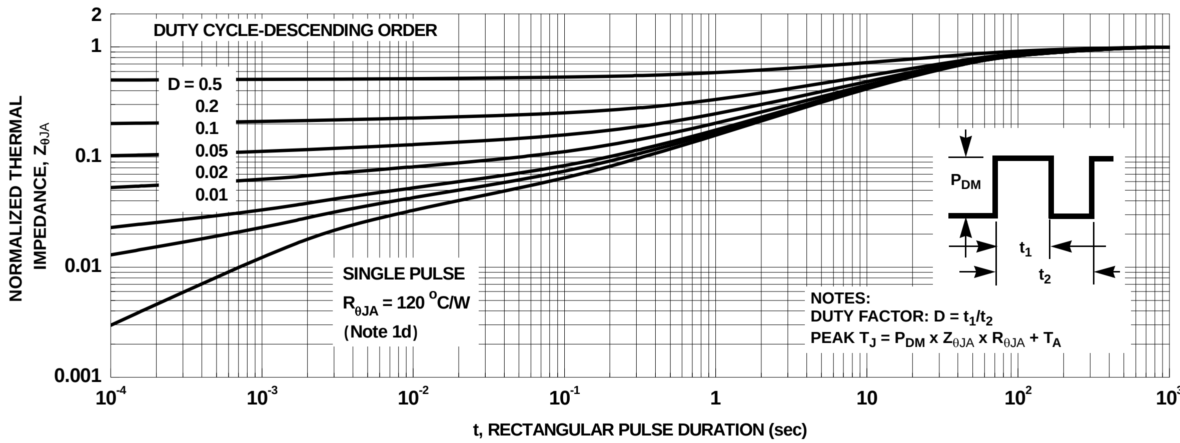


Figure 24. Junction-to-Ambient Transient Thermal Response Curve

Typical Characteristics (continued)

SyncFET™ Schottky body diode Characteristics

Fairchild's SyncFET™ process embeds a Schottky diode in parallel with PowerTrench® MOSFET. This diode exhibits similar characteristics to a discrete external Schottky diode in parallel with a MOSFET. Figure 25 shows the reverse recovery characteristic of the FDMS7602S.

Schottky barrier diodes exhibit significant leakage at high temperature and high reverse voltage. This will increase the power in the device.

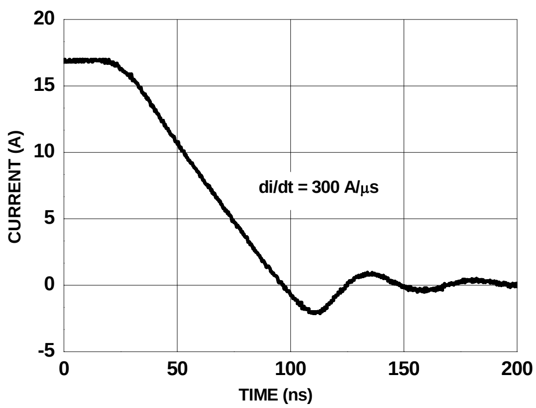


Figure 25. FDMS7602S SyncFET™ Body Diode Reverse Recovery Characteristic

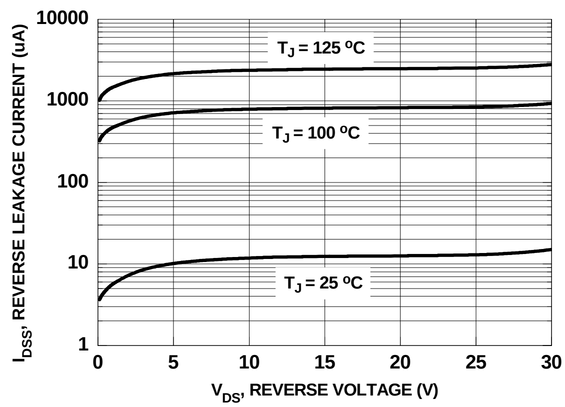
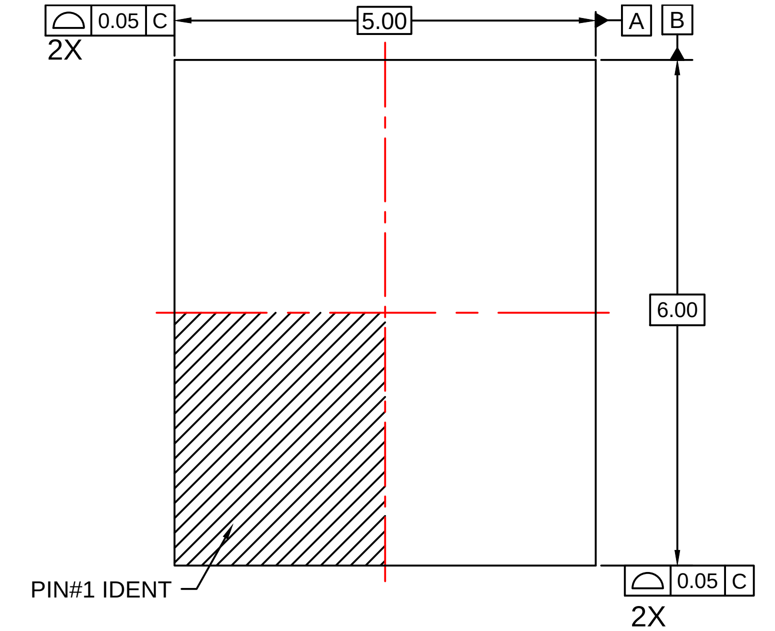
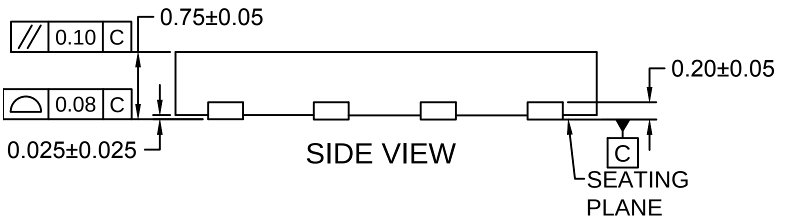
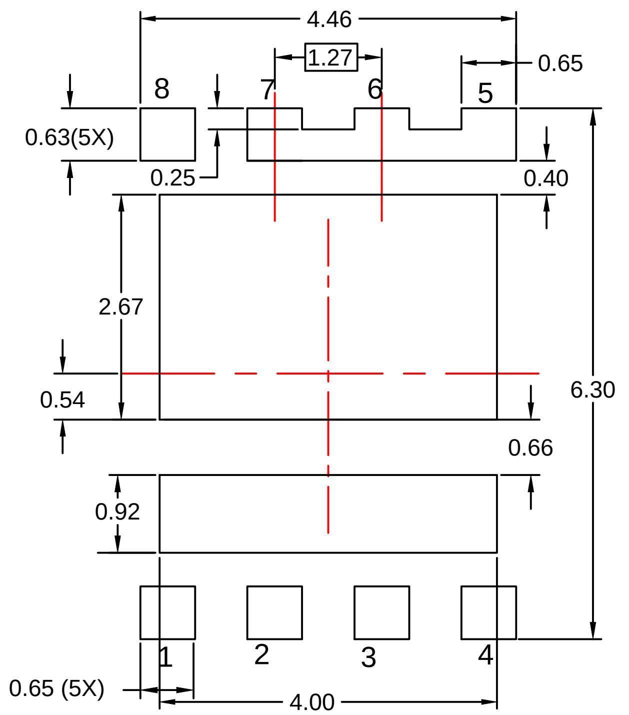


Figure 26. SyncFET™ Body Diode Reverse Leakage vs. Drain-Source Voltage

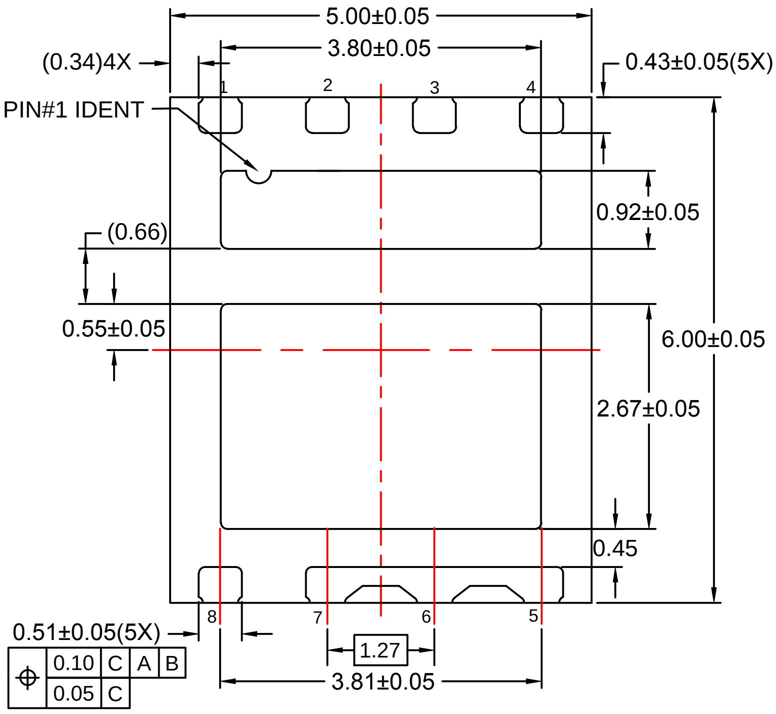




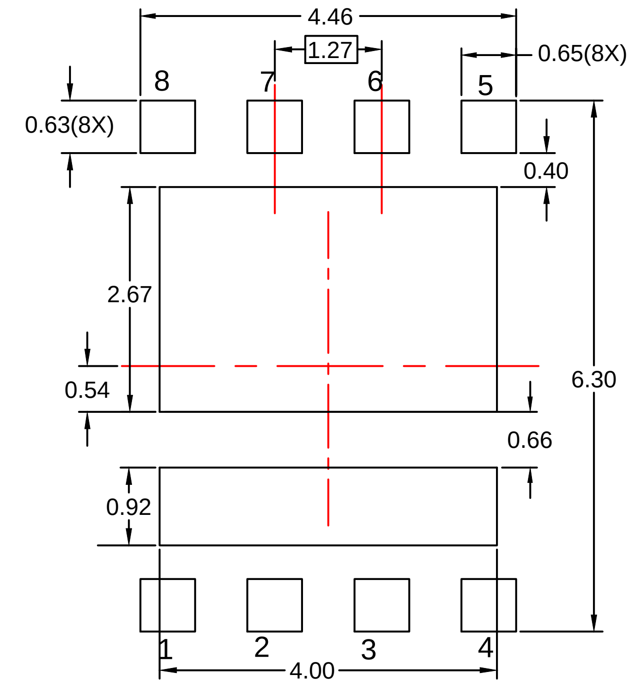
SIDE VIEW



RECOMMENDED LAND PATTERN
(OPTION 1 - FUSED LEADS 5,6,7)



BOTTOM VIEW



RECOMMENDED LAND PATTERN
(OPTION 2 - ISOLATED LEADS)

NOTES:

A. PACKAGE DOES NOT FULLY CONFORM TO JEDEC STANDARD.

B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.

D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.

E. DRAWING FILENAME: MKT-MLP08Prev2.

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EfficientMax™
ESBC™
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MicroFET™
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2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

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